

DEPARTMENT OF MECHATRONICS

VII SEMESTER B. TECH

END SEM EXAM, JULY-NOV 2022

SUBJECT: Micro Electro Mechanical Systems

Subject Code: MTE 4077

Date:21/11/2022

Time: 2:00 PM TO 5:00 PM

MAX. MARKS: 50

✤ Answer ALL the questions.

Missing data could be suitably assumed and justified.

Q. No.		Μ	СО	РО	BL
1A	Illustrate the working principle of chemical sensors, and mention the types of transduction principles used in the chemical sensor.	4	CO1	PO1,2,3	Apply
1B	Discuss the differences between microelectronics and microsystems concerning MEMS technology.	4	CO1	PO1,2,3	Unde rstan d
1C	Determine the voltage output of the four terminal micro thermopiles. The wire material (chrome /constantan) coefficient of 58.7 μ V/ 0 C can receive 500K radiation at a hot junction.	2	CO2	PO1,2,3 ,4,5	Analy ze
2A	Investigate the change of resistance in the piezo resistor attached to the diaphragm of the pressure sensor. There are four identical piezo resistors, A, B, C, and D, diffused in the locations at the top face of the silicon die, as shown in Fig. 1. The square plane geometry of the diaphragm that is subjected to uniform pressure loading of 70MPa at the top surface, the bending moments normal to all edges are equal in magnitudes. Thus, $\sigma_L = \sigma_T = \sigma_{max}$. Resistors A and D are subjected predominantly to the transverse stress component π_T , which is normal to the horizontal edges, whereas, resistors B and C are subjected to the longitudinal stress πL , which is normal to the vertical edges.	4	CO2	PO1,2,3 ,4,5	Creat ing

	Note: $\sigma_{\max} = \frac{0.308 p_{a}^{2}}{h^{2}} \qquad \qquad \frac{\Delta R}{R} = \pi_{L} \sigma_{L} + \pi_{T} \sigma_{T}$ $\pi_{L} = \pi_{T} = 0.02 \pi_{44} \qquad \text{Where, } \pi_{44} = 138.1 \text{x} 10^{11} \text{Pa}^{-1}$				
2B	Explain the working principle of microactuators and name the	3	CO1	PO1,2,3	Apply
2C	Examine by considering a piezoelectric material 2 µm thick and 200 µm ×200 µm in area. A voltage of 10 V is applied across the film, which is made of ZnO material and its piezoelectric coefficient and compliance coefficient are $d = 12 \times 10^{-12}$ C/N and $S = 7 \times 10^{-12}$.	3	CO2	PO1,2,3 ,4,5	Analy ze
	Thickness (t)				
	$D = dT + \varepsilon E \qquad s = ST + d' E$				
	a) Compute the total deformation in the direction of the electric field shown in Fig 2, when no force is applied.b) Calculate the magnitude of the maximum force that can be applied to prevent the deformation of the material.				
3A	A thin piezoelectric crystal film, PZT, is used to transduce the signal in a micro accelerometer involving a cantilever beam made of silicon. The accelerometer is designed for a maximum acceleration/deceleration of 10g. The PZT transducer is located at the support of the cantilever beam where the maximum strain exists (near the support) during the bending of the beam, as illustrated in Fig.3.	5	CO2	PO1,2,3 ,4,5	Evalu ate
	$\begin{array}{c} 2 \ \mu m \\ 0 \ \mu m \\ 0 \ m n \\$				
	Fig.3 Piezoelectric transducer on a beam-accelerometer				
	Determine the electrical voltage output from the PZT film at a maximum acceleration/deceleration of 10 g.				

	Note: Young's Modulus of silicon beam E=1.9x 10 ¹¹ Pa Piezoelectric coefficient d=480x10 ⁻¹² m/V				
3B	What is pull-in voltage, and prove that deflection is less than or equal to d/3?	3	CO2	PO1,2,3 ,4,5	Analy ze
3C	Find the reduction of electrostatic forces generated by a pair of parallel plate electrodes if the length and width of these plates are reduced by a factor of 10.	2	CO2	PO1,2,3 ,4,5	Analy ze
	Note: $F=0.5 \text{ CV}^2/d$				
4A	Determine the pull-in voltage of the cantilever beam with a spring constant of 0.0567 N/m. The overlapping length and width beam is 300 μ m and 5 μ m. The gap between a parallel plate capacitor is 1 μ m, and the structure of the micro-actuated device is shown in Fig. 4. Note: Young's modulus of the beam material is 190 GPa, and the permittivity of air is 8.854x10 ⁻¹² F/m. Polysilicon beam F_e	4	CO2	PO1,2,3 ,4,5	Evalu ate
4B	Sketch and explain Czochralski's method for producing single- crystal silicon.	3	CO3	PO1,2	Apply
4C	Discuss the basic processes used in microfabrication and compare the difference between +ve and -ve resist.	3	CO4	PO1,2,3 ,5,8	Analy ze
5A	Describe the physical vapor deposition method and list the types of PVD methods.	4	CO4	PO1,2,3 ,5,8	Unde rstan d
5B	Discuss the major steps and advantages of the LIGA process.	3	CO4	PO1,2,3 ,5,8	Apply
5C	Illustrate the three levels of microsystem packaging.	3	CO4	PO1,2,3 ,5,8	Apply